



kester®

Technical Data Sheet

SELECT-10™ Selective Solder Flux

Zero-Halogen, No-Clean



Product Description

Kester SELECT-10™ is a zero-halogen no-clean liquid flux designed specifically for the needs of the selective soldering process. Sustained activity within the flux allows for good barrel fill in challenging applications, such as reflowed copper OSP boards or with difficult to solder components. Specific to selective soldering, SELECT-10™ does not spread beyond the spray pattern and will not clog the fluxer head. SELECT-10™ residues are non-tacky for improved cosmetics. SELECT-10™ is classified as ROL0 flux under IPC J-STD-004B. SELECT-10™ is also available as a flux-pen.



Performance Characteristics:

- Zero-halogen (none intentionally added)
- Provides good solderability under air atmosphere
- Controlled flux application, flux does not spread beyond the spray pattern
- Non-corrosive, non-conductive and non-tacky residues
- Ability to provide desired hole-fill with preheat temperatures over 140°C
- No Clogging
- Compliant to GR-78-CORE (Telcordia/Bellcore)
- Classified as ROL0 per J-STD-004B
- Pass SIR in raw and preheating condition
- Also available as a flux-pen



RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive. Additional RoHS information is located at <https://www.kester.com/downloads/environmental>.



Physical Properties

Specific Gravity @ 25°C: 0.835 (typical)

Acid Number (typical): 40.0 mg KOH/g flux

Percent Solids (theoretical): 10%



Reliability Properties

Surface Insulation Resistivity (SIR):

Pass; All Readings $> 1.0 \times 10^9 \Omega$
Tested to J-STD-004B, IPC-TM-650, Method 2.6.3.7
Test Conditions: 40°C, 90% RH, 7 days, 12.5V
Board Prepare Conditions: Room Temperature
Dry with 80°C Preheating. Pattern up through by soldering process, pattern down through by soldering process

Bellcore SIR, IPC: Pass;

All Readings $> 2.0 \times 10^{10} \Omega$
Tested to GR-78 13.1.3
Test Conditions: 35°C, 85% RH, 4 days, 100V
Board Prepare Conditions: Room Temperature
Dry with 80°C Preheating. Pattern up through by soldering process, pattern down through by soldering process

Copper Mirror Corrosion: Low

Tested to J-STD-004B, IPC-TM-650, Method 2.3.32

Corrosion Test: Low

Tested to J-STD-004B, IPC-TM-650, Method 2.6.15

Surface Insulation Resistivity (SIR):

Pass
Tested to J-STD-004A, IPC-TM-650, Method 2.6.3.3
Test Conditions: 85°C, 85% RH, 7 days, 100V
Board Prepare Conditions: Room Temperature
Dry with 80°C Preheating. Pattern up through by soldering process, pattern down through by soldering process

Electrochemical Migration (ECM):

Pass
Tested to J-STD-004B, IPC-TM-650, Method 2.6.14.1
Test Conditions: 65°C, 90% RH, 25 days, 100V
Board Prepare Conditions: Room Temperature
Dry with 80°C Preheating. Pattern up through by soldering process, pattern down through by soldering process

Bono Corrosion Test: Pass;

Fc=1.05%
Test Conditions: 85°C, 85% RH, 15 days, 12V

Halogen Content: None Detected

Tested to J-STD-004-B, IPC-TM-650, Method 2.3.28.1

Flux Application

SELECT-10™ is designed for a drop jet fluxer or ultrasonic fluxer in selective solder applications. Flux deposition should be 186-465 μ gr/cm² (1200-3000 μ gr/in²) of solids.

Process Considerations

Circuit Board Process Recommendations	
Flux deposition	186-465 μ gr/cm ² (1200-3000 μ gr/in ²) of solids
Top side board temperature (bottom preheaters only)	90°C-140°C (194°F-284°F) Maximum bottom side board temperature 145°C
Top side board temperature (top preheaters only)	90°C-145°C (194°F-293°F)
Top side board temperature (bottom and top preheaters) ¹	90°C-140°C (194°F-284°F) Maximum bottom side board temperature 145°C
Recommended preheat profile	Straight ramp to top side board temperature
Solder contact time	2.5-6 seconds
Maximum soldering time in the soldering module with pre-heat at 125°C	2+ hours
Solder bath temperature ²	280°C-320°C (536°F-608°F) for SnCu or SAC alloy 260°C-300°C (500°F-572°F) for Sn63Pb37 alloy

¹ Board is heated from top and bottom there will be a smaller delta temperature between the top and bottom of the board and minimizing the risk of sublimation. **Caution:** Using top and bottom preheaters simultaneously does not insure the center of the board reach proper temperature for soldering.

² The solder bath temperature is a function of the solder nozzle size, circuit board design and components.

Above information is a guideline and it is advisable to note that the optimum settings for a given assembly may vary and this is dependent on the circuit board design, board thickness, components used and equipment used. A design of experiment is recommended to be done to optimize the soldering process.

Flux Control

SELECT-10™ is designed to be sprayed with a drop jet fluxer or ultrasonic fluxer. Incoming solderability inspection of circuit boards and components is advisable as a part of process control to maintain consistent soldering results.

Cleaning

SELECT-10™ residues are non-conductive, non-corrosive and do not require removal in most applications. If residue removal is required it can be removed using commercially available flux residue cleaner. Contact Kester Technical Support for additional assistance..

Storage, Handling and Shelf Life

SELECT-10™ is flammable. Store away from sources of ignition. Shelf life is 1-year from the date of manufacture when handled properly and held at 10-25°C (50-77°F).

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product. Safety Data Sheets are available at <https://www.kester.com/downloads/sds>.